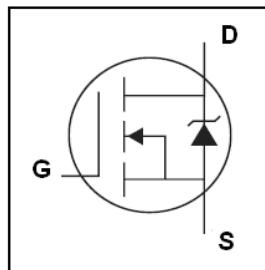


## Features

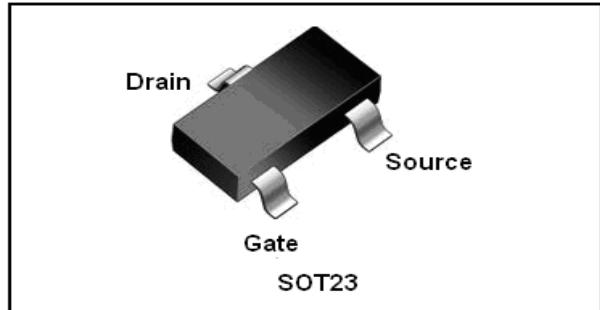
- ◆  $R_{on}(\text{typ.})=30\text{ m}\Omega$  @ $V_{GS}=4.5\text{ V}$
- ◆ Low On-Resistance
- ◆ 150°C Operating Temperature
- ◆ Fast Switching
- ◆ Lead-Free, RoHS Compliant



$V_{DSS} \geq 20\text{ V}$
$R_{DS(on)}=30\text{ m}\Omega$ @ $V_{GS}=4.5\text{ V}$
$R_{DS(on)}=40\text{ m}\Omega$ @ $V_{GS}=2.5\text{ V}$

## Description

VS2302AT designed by the trench processing techniques to achieve extremely low on-resistance. And fast switching speed and improved transfer effective . These features combine to make this design an extremely efficient and reliable device for variety of DC-DC applications.



## Absolute Maximum Ratings

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only; and functional operation of the device at these or any other condition beyond those indicated in the specifications is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability. The thermal resistance and power dissipation ratings are measured under board mounted and still air conditions. Ambient temperature (TA) is 25°C, unless otherwise specified.

Symbol	Parameter	Rating	Unit
<b>Common Ratings (T<sub>c</sub>=25°C Unless Otherwise Noted)</b>			
$V_{GS}$	Gate-Source Voltage	±12	V
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	20	V
$T_J$	Maximum Junction Temperature	150	°C
$T_{STG}$	Storage Temperature Range	-50 to 155	°C
$I_S$	Diode Continuous Forward Current	$T_c=25\text{ }^\circ\text{C}$	3.2 <sup>①</sup>
			A

### Mounted on Large Heat Sink

$I_{DM}$	Pulse Drain Current Tested	$T_c=25\text{ }^\circ\text{C}$	12	A
$I_D$	Continuous Drain Current( $V_{GS}=10\text{ V}$ )	$T_c=25\text{ }^\circ\text{C}$	3.2 <sup>①</sup>	A
		$T_c=100\text{ }^\circ\text{C}$	2.0	
$P_D$	Maximum Power Dissipation	$T_c=25\text{ }^\circ\text{C}$	1.05	W
$R_{\theta JA}$	Thermal Resistance Junction-Ambient		140	°C/W

Symbol	Parameter	Condition	Min	Typ	Max	Unit
<b>Static Electrical Characteristics @ <math>T_J = 25^\circ\text{C}</math> (unless otherwise stated)</b>						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	20	--	--	V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current ( $T_c=25^\circ\text{C}$ )	$V_{\text{DS}}=20\text{V}, V_{\text{GS}}=0\text{V}$	--	--	1	$\mu\text{A}$
	Zero Gate Voltage Drain Current ( $T_c=125^\circ\text{C}$ )	$V_{\text{DS}}=20\text{V}, V_{\text{GS}}=0\text{V}$	--	--	100	$\mu\text{A}$
$I_{\text{GSS}}$	Gate-Body Leakage Current	$V_{\text{GS}}=\pm 10\text{V}, V_{\text{DS}}=0\text{V}$	--	--	$\pm 100$	nA
$V_{\text{GS}(\text{TH})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	0.4	0.6	1.0	V
$R_{\text{DS}(\text{ON})}$	Drain-Source On-State Resistance	$V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=3\text{A}$	--	30	55	$\text{m}\Omega$
$R_{\text{DS}(\text{ON})}$	Drain-Source On-State Resistance	$V_{\text{GS}}=2.5\text{V}, I_{\text{D}}=2\text{A}$	--	40	65	$\text{m}\Omega$
<b>Dynamic Electrical Characteristics @ <math>T_J = 25^\circ\text{C}</math> (unless otherwise stated)</b>						
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=10\text{V}, V_{\text{GS}}=0\text{V}, f=1\text{MHz}$	--	530	--	pF
$C_{\text{oss}}$	Output Capacitance		--	130	--	pF
$C_{\text{rss}}$	Reverse Transfer Capacitance		--	50	--	pF
$Q_g$	Total Gate Charge	$V_{\text{DS}}=10\text{V}, I_{\text{D}}=3\text{A}, V_{\text{GS}}=4.5\text{V}$	--	10	--	nC
$Q_{\text{gs}}$	Gate-Source Charge		--	1.3	--	nC
$Q_{\text{gd}}$	Gate-Drain Charge		--	2.2	--	nC
<b>Switching Characteristics</b>						
$t_{\text{d}(\text{on})}$	Turn-on Delay Time	$V_{\text{DD}}=10\text{V}, I_{\text{D}}=1\text{A}, R_{\text{G}}=6\Omega, V_{\text{GS}}=4.5\text{V}, R_{\text{L}}=5\Omega$	--	12.5	--	nS
$t_r$	Turn-on Rise Time		--	40	--	nS
$t_{\text{d}(\text{off})}$	Turn-Off Delay Time		--	42	--	nS
$t_f$	Turn-Off Fall Time		--	29	--	nS
<b>Source- Drain Diode Characteristics</b>						
$I_{\text{SD}}$	Source-drain current(Body Diode)	$T_c=25^\circ\text{C}$	--	--	$3.2^{\textcircled{1}}$	A
$I_{\text{SDM}}$	Pulsed Source-drain current (Body Diode)		--	--	$12^{\textcircled{1}}$	A
$V_{\text{SD}}$	Forward on voltage	$T_j=25^\circ\text{C}, I_{\text{SD}}=3\text{A}, V_{\text{GS}}=0\text{V}$	--	0.85	1.3	V

Notes: ① Pulse test ; Pulse width $\leq 300\mu\text{s}$ , duty cycle $\leq 2\%$ .

### Typical Characteristics

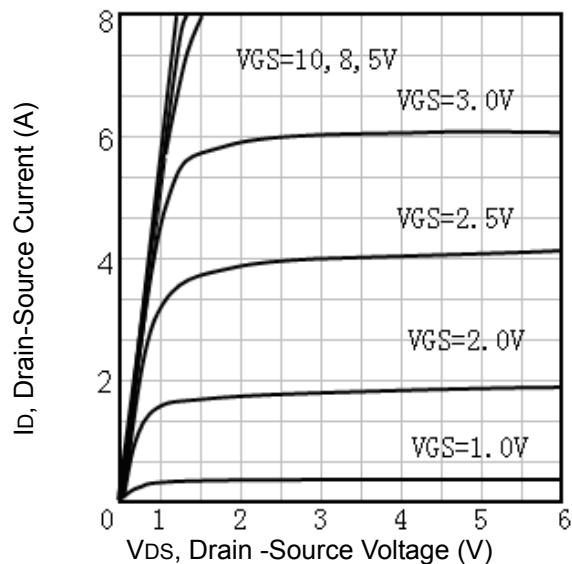


Fig1. Typical Output Characteristics

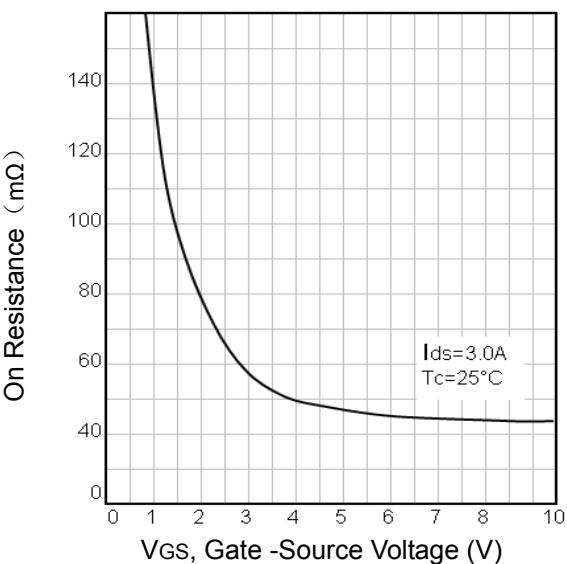


Fig2. Typical Transfer Characteristics

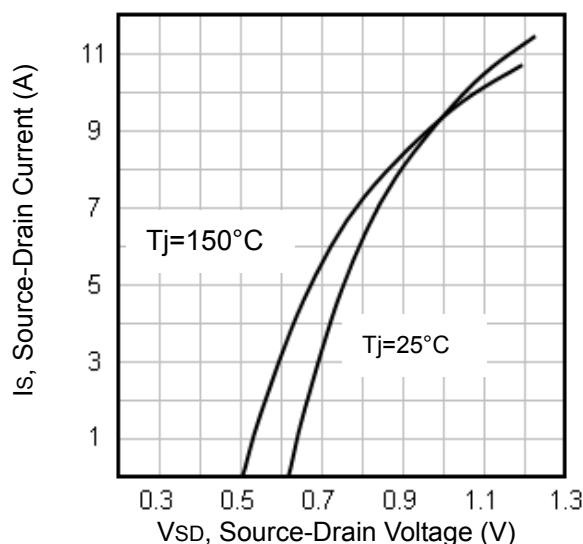


Fig7. Typical Source-Drain Diode Forward Voltage

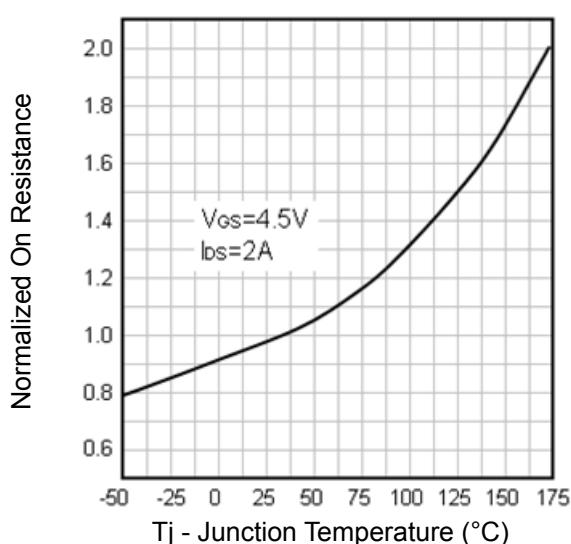


Fig4. Normalized On-Resistance Vs. Temperature

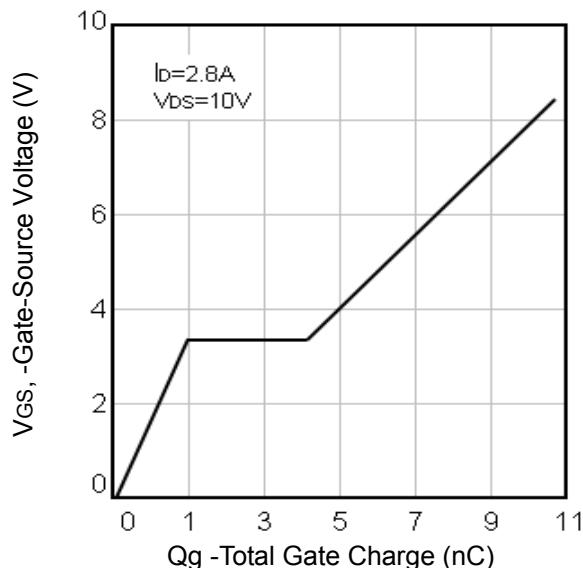


Fig5. Typical Gate Charge Vs. Gate-Source Voltage

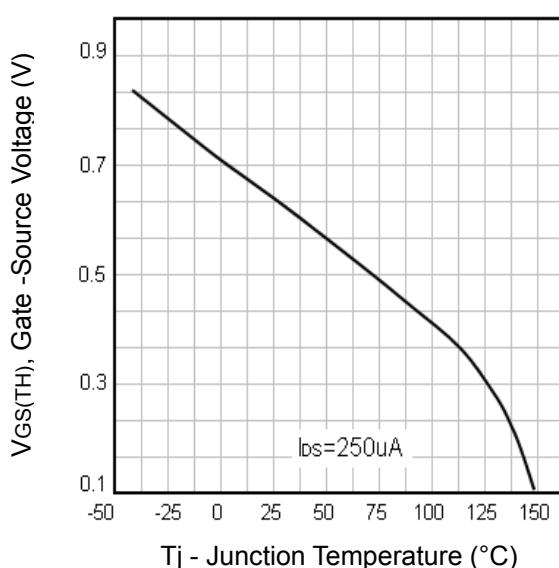
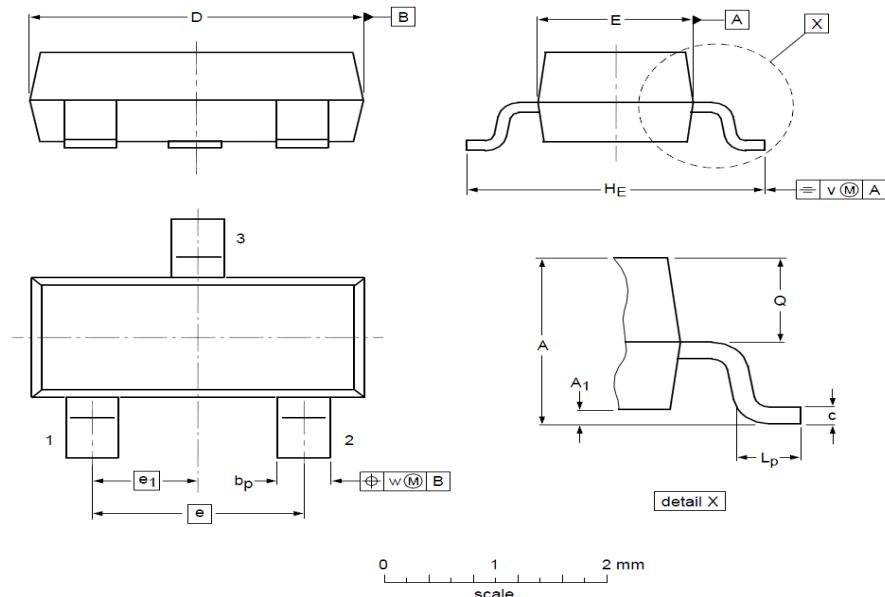


Fig6. Threshold Voltage Vs. Temperature

## SOT23 Mechanical Data



**DIMENSIONS ( unit : mm )**

Symbol	Min	Typ	Max	Symbol	Min	Typ	Max
A	0.90	1.03	1.10	A <sub>1</sub>	0.01	0.05	0.10
b <sub>p</sub>	0.38	0.42	0.48	c	0.09	0.13	0.15
D	2.80	2.92	3.00	E	1.20	1.33	1.40
e	--	1.90	--	e <sub>1</sub>	--	0.95	--
H <sub>E</sub>	2.10	2.40	2.50	L <sub>p</sub>	0.15	0.23	0.45
Q	0.45	0.49	0.55	v	--	0.20	--
w	--	0.10	--				

## Order Information

Product	Marking	Package	Packaging	Min Unit Quantity
VS2302AT	VS22	SOT23	3000/Reel	6000

## Customer Service

### Sales and Service:

Sales@vgsemi.com

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